TOSHIBA BI-CMOS INTEGRATED CIRCUIT SILICON MONOLITHIC

TB31214FNG

PLL FREQUENCY SYNTHESIZER FOR CORDLESS TELEPHONE

FEATURES

• One packaging PLL, VCO and 1st MIX

Low operating voltage : V_{CC} = 2.0~5.5V

 $(Ta \ge -10^{\circ}C, V_{CC} = 1.9 \sim 5.5V)$

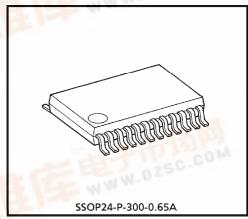
Low current consumption : I_{CC} = 16mA (Typ.)

 Charge pump is constant current type, and is able to change output current by serial data

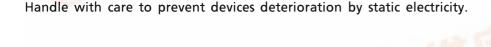
 Reference oscillation circuit is adopted circuit of bipolar, so getting the stable X'tal oscillation circuit

Available standby control for receiver and transmitter independent of each other

• Small package : SSOP24pin (0.65mm pitch)

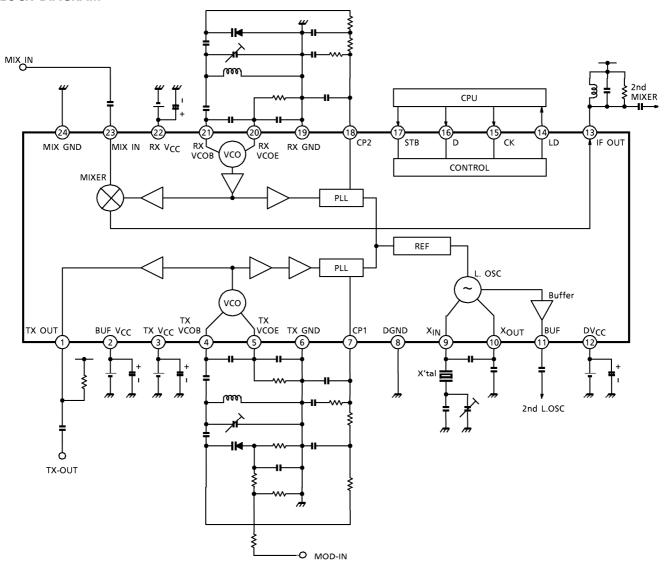


Weight: 0.14g (Typ.)





BLOCK DIAGRAM



PIN FUNCTION

PIN No.	PIN NAME	FUNCTION	INTERNAL EQUIVALENT CIRCUIT
1	TX OUT	Output terminal of RF.	0 2
2	BUF V _{CC}	Power supply of transmitter output, transmitter VCO.	3 TX VCC
3	TX V _{CC}	Power supply for transmitter PLL.	
4	TX VCOB	Base terminal of transistor for transmitter VCO.	(a) (1)
5	TX VCOE	Emitter terminal of transistor for transmitter VCO.	S
6	TX GND	GND terminal for transmitter.	6 TX-GND
7	CP1	Output terminal of charge pump for transmitter. It is constant current output type, and output current is varied by input serial data.	DV _{CC}
8	DGND	GND terminal of PLL.	B DGND
9	X _{IN}	Input terminal of local oscillation. In case of external input, connecting it to this terminal.	DVcc
10	X _{OUT}	Output terminal of local oscillation.	9 2 2 3
11	BUF	Output terminal of BUFFER AMP. The signal of local oscillation is output through BUFFER AMP.	1κΩ
12	DV _{CC}	Power supply of PLL.	8 DGND

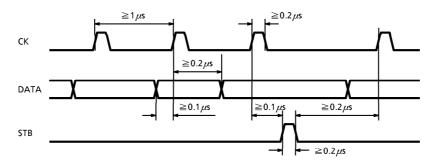
PIN No.	PIN NAME	FUNCTION	I	INTERNAL EQUIVALENT CIRCUIT			
13	IF OUT	MIX output terminal. For open collector output.	RX VCC 13 MIX GND				
14	LD	Output terminal of lock detecto	200Ω 14 200Ω 8 DGND				
15	СК	Input terminal of clock.	15 1kΩ				
16	D	Input terminal of data.	16 7 7				
17	STB	Input terminal of strobe signal.	8 DGND				
18	CP2	Output terminal of charge pum It is constant current output typ is varied by input serial data.		DV _{CC} B DGND			
19	RX GND	GND terminal for receiver.		RX VCC			
20	RX VCOE	Emitter terminal of transistor fo	r receiver VCO.	7			
21	RX VCOB	Base terminal of transistor for r	eceiver VCO.				
22	RX V _{CC}	Power supply for receiver.	RX GND				
23	MIX IN	Input terminal of MIX.	22 RX V _{CC}				
24	MIX GND	GND terminal of MIX.		G G G G G G G G G G G G G G G G G G G			

DESCRIPTION OF FUNCTION AND OPERATION

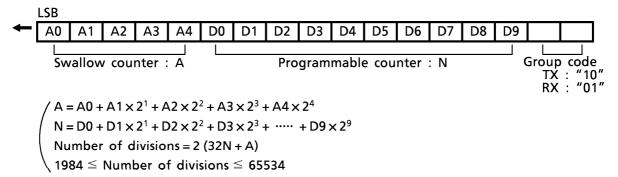
- 1. Entry of serial data
 - Serial data used to control the IC is input through three terminals, CK, D and STB.
 - ① During the rise of a clock pulse, data is fed to the shift register in the IC in order from the LSB.
 - ② Upon the reception of all data, the strobe signal (STB) is made "H".
 - ③ After the reception of a strobe signal (STB) of the "H" level, the data stored in the shift register is transferred to the latch in the block selected by the group code, whereby the IC is controlled.
 - ④ A counters start to operate after the reception of a strobe signal (STB) of the "L" level.
 - The three terminal, CK, D and STB, contains Schmitt trigger circuits to prevent the data errors by noise, etc.
 - O Serial data group and group code
 - The IC has control divided into four groups so that they may be controlled independent of one another. Each group is identified by a 2bit group code attached at the data end.

CODE	ITEM
10	Number of divisions by TX programmable divider
01	Number of divisions by RX programmable divider
11	Number of divisions by reference divider (X _{IN})
00	Optional control

O Serial data input timing

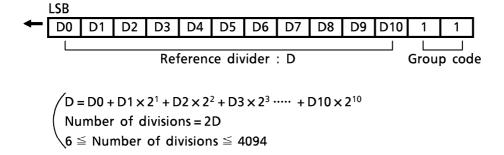


- 2. Programmable dividers (TX, RX)
 - These programmable dividers are composed of a 5bit swallow counter (5bit programmable divider), a 10bit programmable counter, and a two-modulars prescaler providing 64 and 66 divisions.
 - Swallow counter system is adopted to set high reference frequency.
 - Sending certain data to the swallow counter and the programmable counter allows the setting of any of 1984 to 65534 divisions (multiple of two).
 - The programmable counter and swallow counter are set by each channel. Each channel is specified by a group code.



3. Reference divider

- This block generates the reference frequency for the PLL.
- The reference divider is composed of a 11bit reference divider and a half fixed divider.
- Sending certain data to the reference divider allows the setting of any of 6 to 4094 divisions (multiple of two).



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The example of setting number of divisions

In case of

Reference frequency : 21.25MHz Start VCO frequency : 380.2125MHz Channel step : 12.5KHz

O Set up phase comparator frequency

Since a programmable divider is multiple of two, phase comparator frequency is set a half of frequency step.

Phase comparator frequency = $(12.5 \times 10^3 \div 2) = 6.25$ KHz

O Set up programmable divider divisions

$$380.2125 \times 10^6 \div (12.5 \times 10^3 \div 2) = 60834$$

 $60834 = 2 (32N + A)$
 $N = 950$ $A = 17$

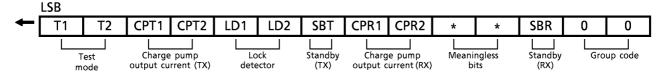
O Set up reference divider divisions

$$21.25 \times 10^6 \div (12.5 \times 10^3 \div 2) = 3400$$

2D = 3400
D = 1700

4. Optional control

- The optional control below is available.
 - ① Test mode (Usually set up T1 = T2 = "0").
 - 2 Control of the charge pump output current for each channel.
 - 3 Output terminal for Lock detector.
 - 4 Standby control of each channel.



T1, T2 : Bit for test mode

CPT1, 2 : Switchover bit for charge pump output current (TX) CPR1, 2 : Switchover bit for charge pump output current (RX)

LD1, 2 : Control bit for lock detector output

SBT, SBR: Standby control bit (TX, RX)

* : Disregard any data (Meaningless bits)

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- Description of options including their control
 - 1 Test mode (T1, T2)

Bit "T1, T2" is for test mode. In other than the test mode, set this bit at "0".

2 Control of charge pump output current (CPT, CPR)

This IC uses a constant current output type charge pump circuit. Output current is varied by controlling "CPT1, 2".

CHARGE PUMP OUTPUT CURRENT

CONTR	OL BIT	CHARGE PUMP		
CPT1	CPT2	OUTPUT CURRENT		
0	0	±0μA		
0	1	± 100μA		
1	0	± 200μA		
1	1	± 400μA		

High speed lock up is possible by switching charge pump output current.

(Note) CPR is the similar way

3 Lock detector output

When phase comparator detects phase difference, LD terminal (pin 14) outputs "H". When phase comparator locks, LD terminal outputs "L". On standby, outputs "L".

LD terminal output is controlled by "SBT", "SBR", "LD1" and "LD2".

LD terminal output is open drain output.

CONTR	OL BIT	LOCK DETECTOR
LD1	LD2	OUTPUT STATE
0	0	Н
0	1	TX Only detect
1	0	RX Only detect
1	1	TX * RX

Standby control (SBT, SBR)

Available standby control for receiver and transmitter independent of each other.

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CONTR	OL BIT		STATE	
SBT	SBR	TX	RX	REF
0	0	ON	ON	ON
0	1	ON	OFF	
1	0	OFF	ON	
1	1	OFF	OFF	\

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5. Reference frequency oscillation circuit and buffer amplifier

This IC has a stable oscillation circuit composed of bipolar. In case of inputting the external reference frequency directly, use X_{IN} terminal (pin 9). For the common use of X'tal of the reference frequency oscillation circuit for the PLL and X'tal of local oscillation to 2'nd MIX, output terminal of local oscillation signal with buffer amplifier (pin 11) may be used.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Power Supply Voltage	Vcc	6	V
Power Dissipation	PD	780	mW
Operating Temperature	T _{opr}	- 30~85	°C
Storage Temperature	T _{stg}	- 55∼150	°C

ELECTRICAL CHARACTERISTICS (Unless otherwise specified, Ta = 25°C, V_{CC} = 2.2V)

CHARACTERISTIC	SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Operating Power	Vac		Ta = −30~ +85°C	2.0	2.2	5.5	\ \
Supply Voltage	V _{CC}		$Ta = -10 \sim +85 ^{\circ}C$	1.9	2.2	5.5	V
Operating Power Supply Current	^I cco	1	TX, RX = ON (Open VCOE)		16	22	mA
Waiting Current Consumption	lccs	1	TX, RX = OFF		950	1300	μΑ

PLL

In most Eventual and	(RX)	FRXin	4	$VRX_{in} = 93dB\mu V$ *1	200	_	400	N/11-
Input Frequency	(TX)	FTXin	4	$VTX_{in} = 93dB\mu V$ *1	200	_	400	MHz
Input Concitivity	(RX)	VRXin	4	FRX _{in} = 200~400MHz *1	93	_	107	dD\/
Input Sensitivity	(TX)	VTX _{in}	4	FTX _{in} = 200~400MHz *1	93		107	$dB\muV$
Charge Pump Output Current 1		I _{CP1}	2	V _{CP} = 1.1V	_	±0	_	μ A
Charge Pump Output Current 2		I _{CP2}	2	V _{CP} = 1.1V	_	± 100	_	μΑ
Charge Pump Output Current 3		I _{CP3}	2	V _{CP} = 1.1V	_	± 200	_	μ A
Charge Pump Output Current 4		I _{CP4}	2	V _{CP} = 1.1V	_	± 400	_	μΑ
Charge Pump OFF Leak Current		ICPOFF	2	V _{CP} = 1.1V, Standby mode	- 1		+ 1	μΑ
CK Input Frequency	/	FCK	_	_	_		1.0	MHz
Input Voltage	(H)	V _{IH}		CK, DATA, STB each terminal	0.8 × V _C C	Vcc	5.7	V
input voitage	(L)	V_{IL}		CK, DATA, STB each terminal	-0.2	0	0.2 × V _{CC}	V
Input Current	(H)	lіН		CK, DATA, STB each terminal VIH = 6V	_		1	
(l _{IL}		CK, DATA, STB each terminal V _{IL} = 6V	_		1	- μΑ
LD Terminal Resistance ON		R _{LD}	3	LD = "L"	_	500	_	Ω
LD Terminal OFF Leak Current		^I LDOFF	_	_	- 1	_	+1	μΑ

REF

CHARACTERISTIC	SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
XIN Operating Frequency	FX _{in}	5	$VX_{in} = 105dB\mu V$ Sin-wave	5	21.25	25	MHz
XIN Input Level	VXin	5	FX _{in} = 21.25MHz	102	105	112	$dB\muV$

1st MIX

Operating Input	FMIX	6		200		400	MHz
Frequency	FIVIIA	O	_	200	_	400	IVITZ
MIX Conversion Gain	GVMIX	6	Input 50 Ω , Load : Output 750 Ω	15	18	22	dB
3rd Intercept Point	IP3		_	_	108	_	$dB\muV$
1dB Compression Level	1dBCP	6	_	_	99	_	$dB\muV$

REFERENCE VALUE

Input/output resistance, input/output capacitance (Typ.)

PIN No.	PIN NAME	RESISTANCE (Ω)	CAPACITANCE (pF)
23	MIX IN	620	3.1
13	IF OUT	11K	2.5

RECEIVER VCO

Operating Frequency	FRVCO	_	_	200	_	400	MHz
C/N Characteristic	CNR	_	PLL loop shaping *2	_	72		dB

TRANSMITTER VCO

Operating Frequency	FTVCO	_	_	200	_	400	MHz
C/N Characteristic	CNT	_	PLL loop shaping *2	_	72	_	dB

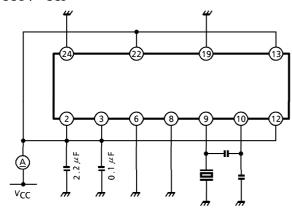
*1 : In case of input $\mathbf{50}\Omega$ from VCOE terminal

*2 : Detuning frequency = 12.5kHz, Band range = 8kHz

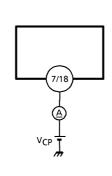
*3 : Use for operating TX V_{CC}-PLL V_{CC}, RX V_{CC}-PLL V_{CC} is within ±0.2V.

TEST CIRCUIT

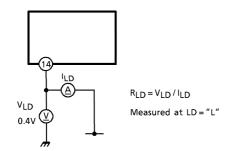
1. Icco、Iccs



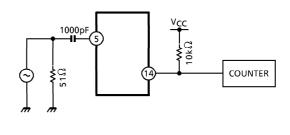
2. I_{CP}



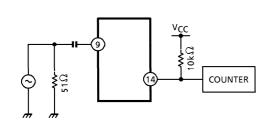
3. R_{LD}



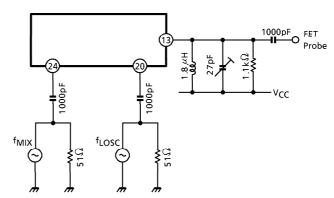
4. V_{TXIN}, V_{XIN}

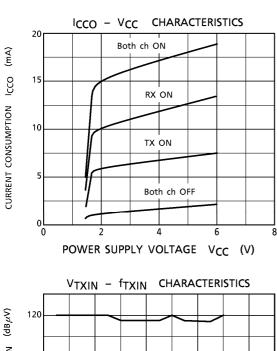


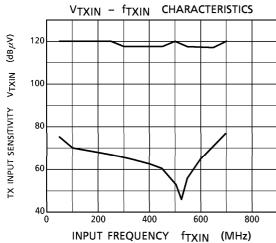
5. V_{XIN}

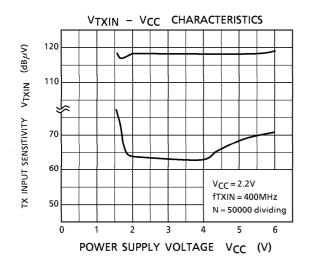


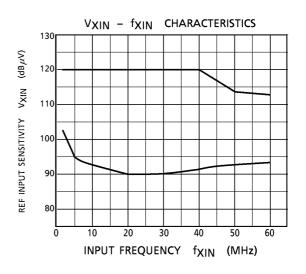
6. G_{VMIX}

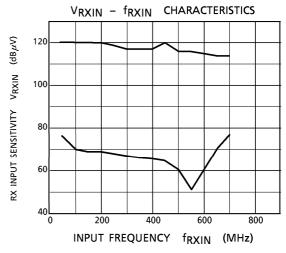


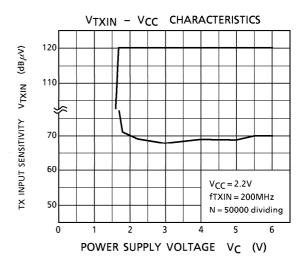


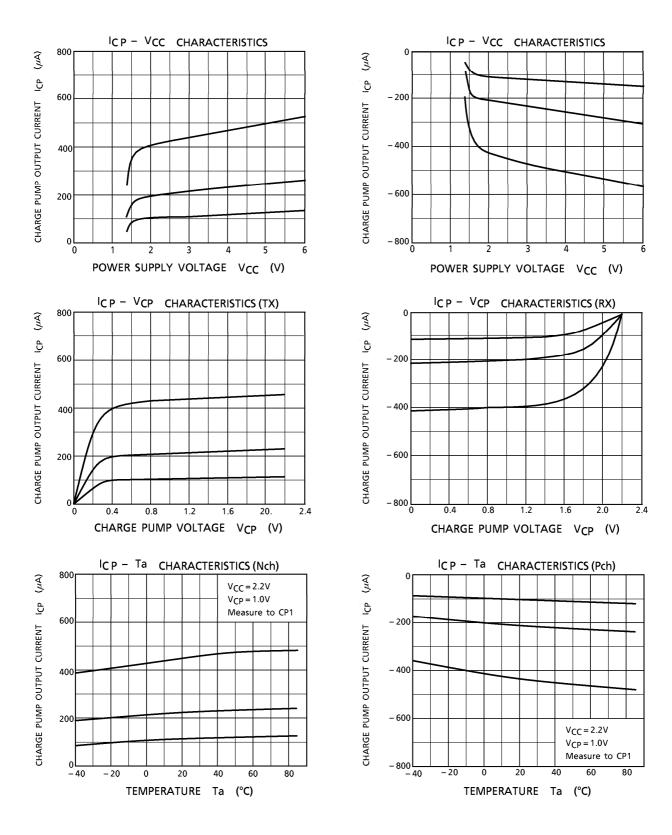


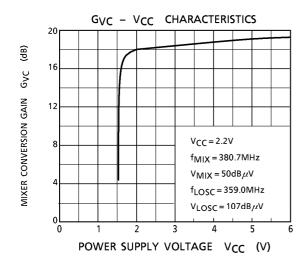


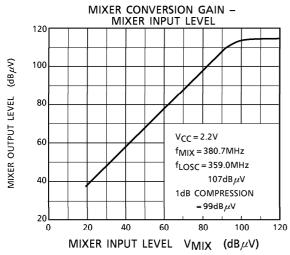


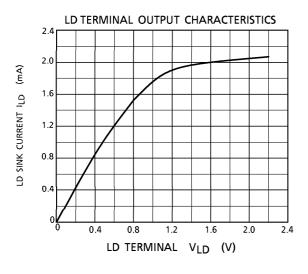


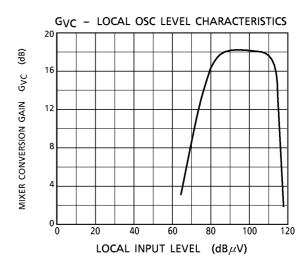


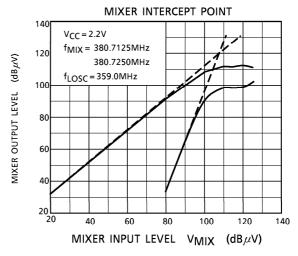




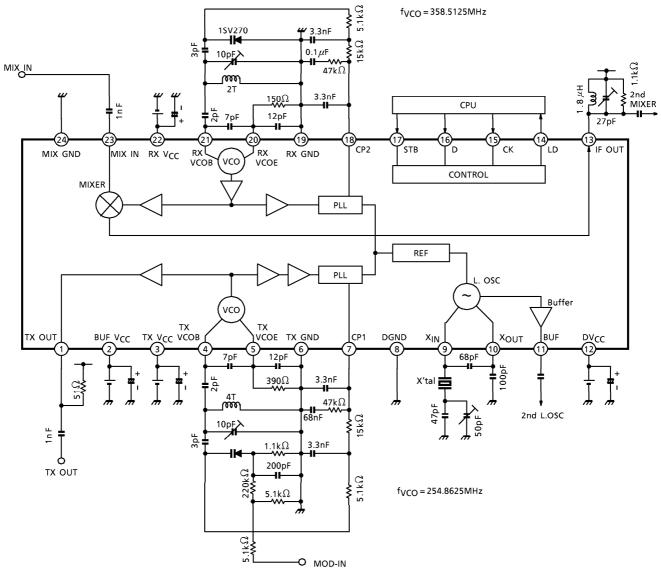




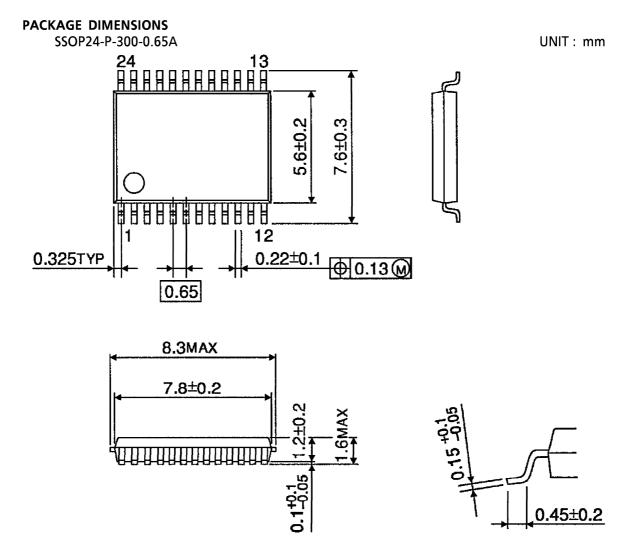




APPLICATION CIRCUIT



Hand set of coldless phone $V_{CC} = 2.2 [V]$ constant



Weight: 0.14g (Typ.)

About solderability, following conditions were confirmed

- Solderability
 - (1) Use of Sn-63Pb solder Bath
 - · solder bath temperature = 230°C
 - · dipping time = 5 seconds
 - · the number of times = once
 - · use of R-type flux
 - (2) Use of Sn-3.0Ag-0.5Cu solder Bath
 - · solder bath temperature = 245°C
 - · dipping time = 5 seconds
 - · the number of times = once
 - · use of R-type flux

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